



STGW35NB60S

N-channel 35A - 600V - TO-247
Low drop PowerMESH™ IGBT

Features

| Type | V _{CES} | V _{CE(sat)} (Max)@ 25°C | I _C @100°C |
|-------------|------------------|-------------------------------------|--------------------------|
| STGW35NB60S | 600V | < 1.7V | 35A |

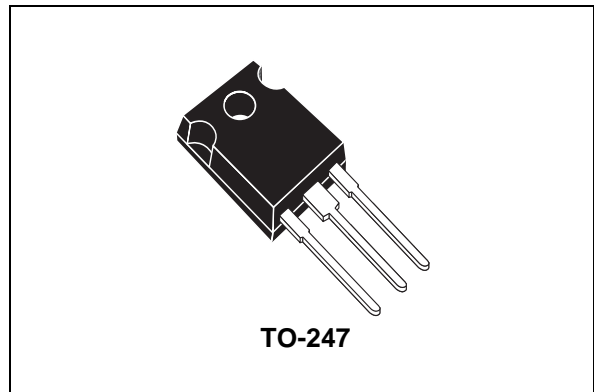
- Low on-voltage drop (V_{CEsat})
- Low input capacitance
- High current capability

Description

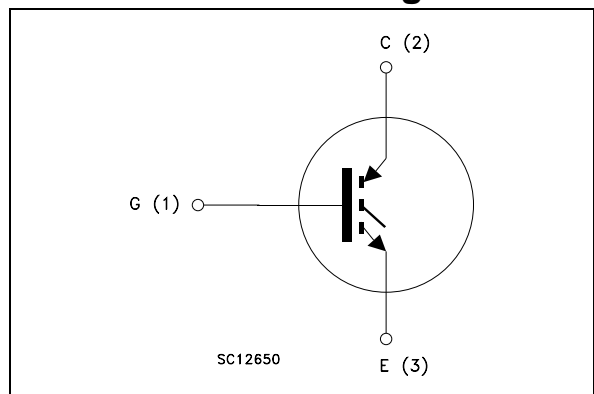
Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances.

Applications

- Light dimmer
- HID
- Welding
- Motor control
- Static relays



Internal schematic diagram



Order code

| Part number | Marking | Package | Packaging |
|-------------|-----------|---------|-----------|
| STGW35NB60S | GW35NB60S | TO-247 | Tube |

Contents

| | | |
|----------|--|-----------|
| 1 | Electrical ratings | 3 |
| 2 | Electrical characteristics | 4 |
| | 2.1 Electrical characteristics (curves) 6 | |
| 3 | Test Circuits | 9 |
| 4 | Package mechanical data | 10 |
| 5 | Revision history | 12 |

1 Electrical ratings

Table 1. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|----------------|---|-------------|------|
| V_{CES} | Collector-emitter voltage ($V_{GS} = 0$) | 600 | V |
| $I_C^{(1)}$ | Collector current (continuous) at 25°C | 70 | A |
| $I_C^{(1)}$ | Collector current (continuous) at 100°C | 35 | A |
| $I_{CM}^{(2)}$ | Collector current (pulsed) | 250 | A |
| V_{GE} | Gate-emitter voltage | ± 20 | V |
| P_{TOT} | Total dissipation at $T_C = 25^\circ\text{C}$ | 200 | W |
| T_j | Operating junction temperature | - 55 to 150 | °C |

1. Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{JMAX} - T_C}{R_{THJ-C} \cdot V_{CESAT(MAX)}(T_C, I_C)}$$

2. Pulse width limited by max. junction temperature

Table 2. Thermal resistance

| | | Value | Unit |
|-----------|---|-------|------|
| Rthj-case | Thermal resistance junction-case max | 0.625 | °C/W |
| Rthj-amb | Thermal resistance junction-ambient max | 50 | °C/W |

2 Electrical characteristics

($T_{CASE} = 25\text{ °C}$ unless otherwise specified)

Table 3. Static

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---------------|--|--|------|-------------|-----------|--------------------------------|
| $V_{BR(CES)}$ | Collector-Emitter Breakdown Voltage | $I_C = 1\text{mA}$, $V_{GE} = 0$ | 600 | | | V |
| $V_{CE(SAT)}$ | Collector-Emitter Saturation Voltage | $V_{GE} = 15\text{V}$, $I_C = 20\text{A}$, $V_{GE} = 15\text{V}$, $I_C = 20\text{A}$, $T_J = 125\text{°C}$ | | 1.25 1.2 | 1.7 | V V |
| $V_{GE(th)}$ | Gate Threshold Voltage | $V_{CE} = V_{GE}$, $I_C = 250\mu\text{A}$ | 2.5 | | 5 | V |
| I_{CES} | Collector-Emitter Leakage Current ($V_{GE} = 0$) | $V_{CE} = \text{Max Rating}$, $V_{CE} = \text{Max Rating}$, $T_C = 125\text{°C}$ | | | 10 100 | μA μA |
| I_{GES} | Gate-Emitter Leakage Current ($V_{CE} = 0$) | $V_{GE} = \pm 20\text{V}$, $V_{CE} = 0$ | | | ± 100 | nA |
| g_{fs} | Forward Transconductance | $V_{CE} = 10\text{V}$, $I_C = 18\text{A}$ | | 20 | | S |

Table 4. Dynamic

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|-----------|------------------------------|---|------|------|------|------|
| C_{ies} | Input Capacitance | $V_{CE} = 25\text{V}$, $f = 1\text{ MHz}$, $V_{GE} = 0$ | | 1820 | | pF |
| C_{oes} | Output Capacitance | | | 167 | | pF |
| C_{res} | Reverse Transfer Capacitance | | | 27 | | pF |
| Q_g | Total Gate Charge | $V_{CE} = 480\text{V}$, $I_C = 20\text{A}$, $V_{GE} = 15\text{V}$, (see Figure 16) | | 83 | 115 | nC |
| Q_{ge} | Gate-Emitter Charge | | | 10 | | nC |
| Q_{gc} | Gate-Collector Charge | | | 27 | | nC |
| I_{CL} | Turn-Off SOA Minimum Current | $V_{clamp} = 480\text{V}$, $T_J = 125\text{°C}$ $R_G = 100\Omega$ | 80 | | | A |

Table 5. Switching on/off (inductive load)

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---|---|---|------|---------------------|------|-------------------------------|
| $t_{d(on)}$ t_r $(di/dt)_{on}$ | Turn-on Delay Time Current Rise Time Turn-on Current Slope | $V_{CC} = 480V, I_C = 20A$ $R_G = 100\Omega, V_{GE} = 15V,$ see Figure 15 and 17 | | 92 70 340 | | ns ns A/ μ s |
| $t_{d(on)}$ t_r $(di/dt)_{on}$ | Turn-on Delay Time Current Rise Time Turn-on Current Slope | $V_{CC} = 480V, I_C = 20A$ $R_G = 100\Omega, V_{GE} = 15V,$ $T_j = 125^\circ C$ see Figure 15 and 17 | | 80 73 320 | | ns ns A/ μ s |
| $t_r(V_{off})$ $t_{d(off)}$ t_f | Off Voltage Rise Time Turn-off Delay Time Current Fall Time | $V_{CC} = 480V, I_C = 20A,$ $R_{GE} = 100\Omega, V_{GE} = 5V,$ see Figure 15 and 17 | | 0.78 1.1 0.79 | | μ s μ s μ s |
| $t_r(V_{off})$ $t_{d(off)}$ t_f | Off Voltage Rise Time Turn-off Delay Time Current Fall Time | $V_{CC} = 480V, I_C = 20A,$ $R_{GE} = 100\Omega, V_{GE} = 15V,$ $T_j = 125^\circ C$ see Figure 15 and 17 | | 1.1 2.4 1.2 | | μ s μ s μ s |

Table 6. Switching energy (inductive load)

| Symbol | Parameter | Test conditions | Min. | Typ. | Max. | Unit |
|---|---|---|------|----------------------|------|----------------|
| E_{on} $E_{off}^{(1)}$ E_{ts} | Turn-on Switching Losses Turn-off Switching Losses Total Switching Losses | $V_{CC} = 480V, I_C = 20A$ $R_G = 100\Omega, V_{GE} = 15V,$ see Figure 15 and 17 | | 0.84 7.4 8.24 | | mJ mJ mJ |
| E_{on} $E_{off}^{(1)}$ E_{ts} | Turn-on Switching Losses Turn-off Switching Losses Total Switching Losses | $V_{CC} = 480V, I_C = 20A$ $R_G = 100\Omega, V_{GE} = 15V,$ $T_j = 125^\circ C$ see Figure 15 and 17 | | 0.86 11.5 12.4 | | mJ mJ mJ |

1. Turn-off losses include also the tail of the collector current

2.1 Electrical characteristics (curves)

Figure 1. Output characteristics

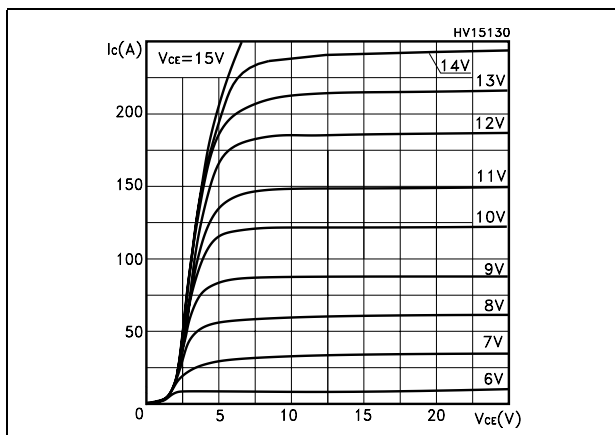


Figure 2. Transfer characteristics

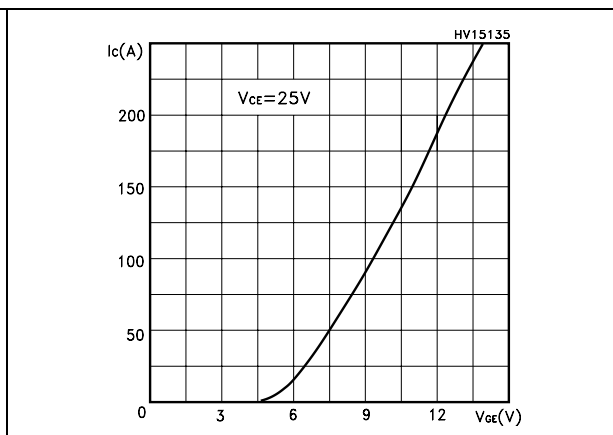


Figure 3. Transconductance

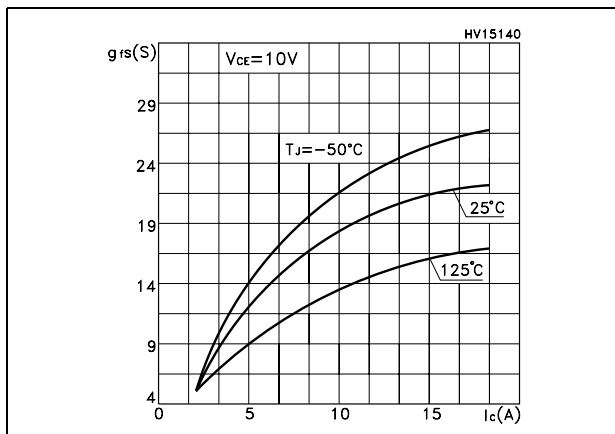


Figure 4. Normalized collector-emitter on voltage vs temperature

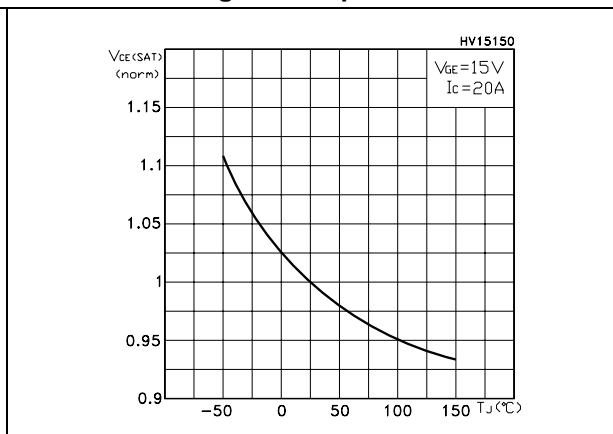


Figure 5. Collector-emitter on voltage vs collector current

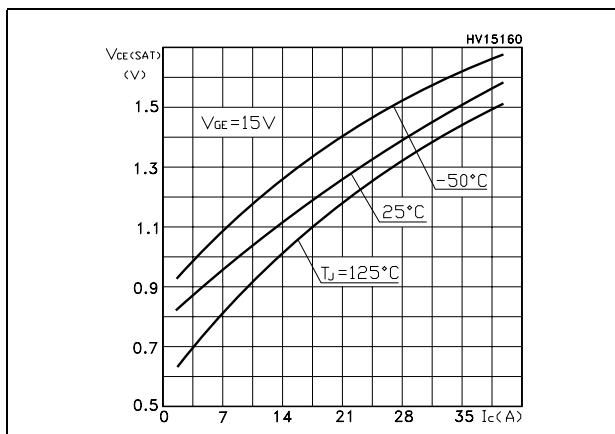


Figure 6. Gate threshold vs temperature

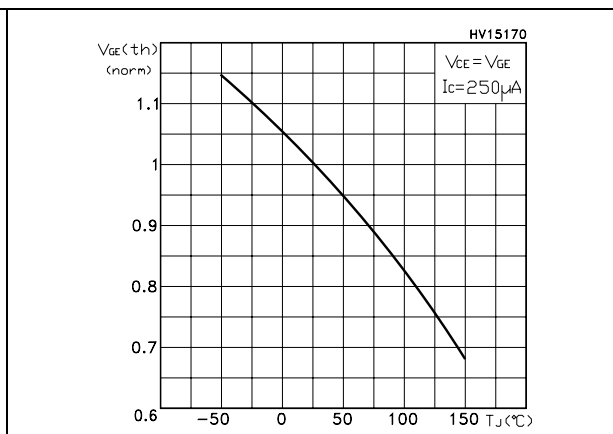


Figure 7. Normalized breakdown voltage vs temperature

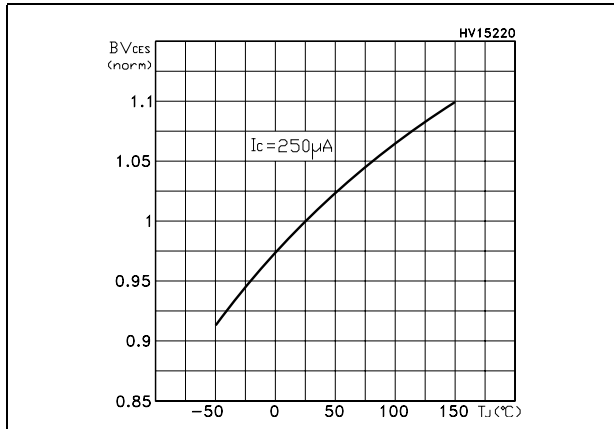


Figure 8. Gate charge vs gate-emitter voltage

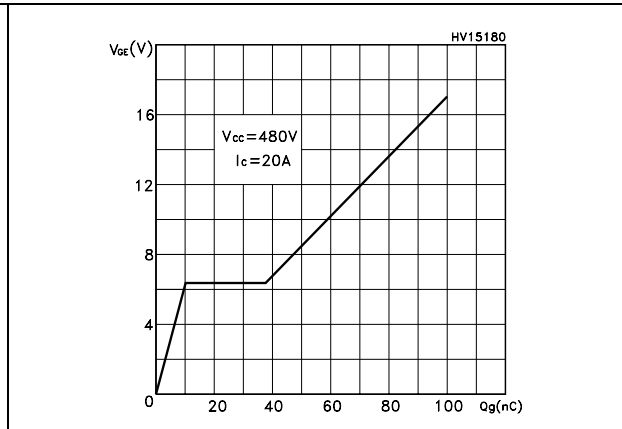


Figure 9. Capacitance variations

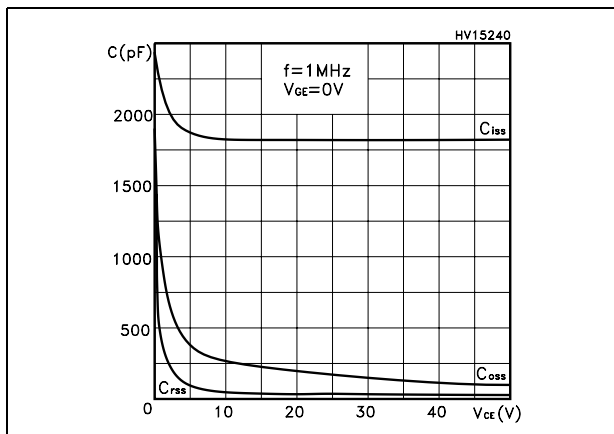


Figure 10. Switching losses vs gate charge

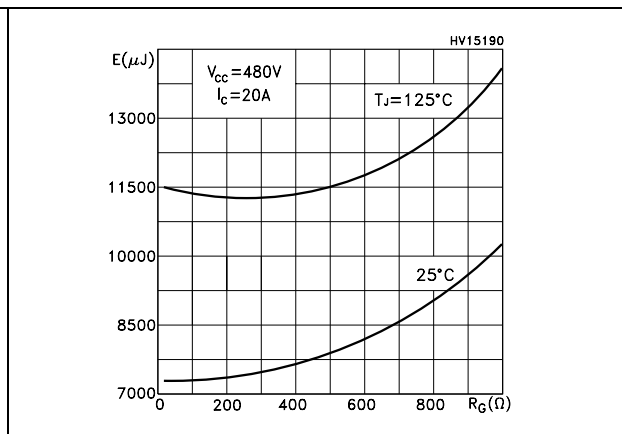


Figure 11. Switching losses vs temperature

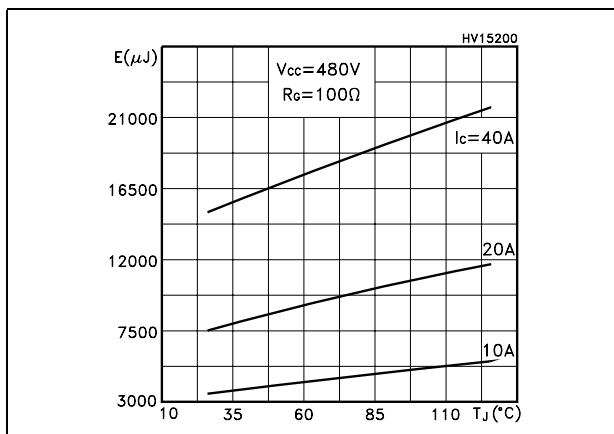


Figure 12. Switching losses vs collector current

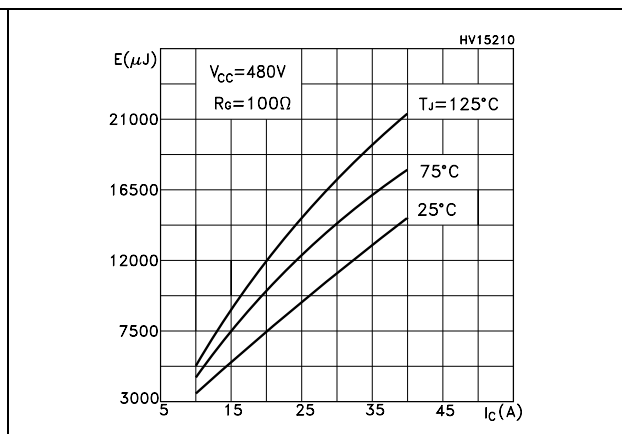


Figure 13. Thermal impedance

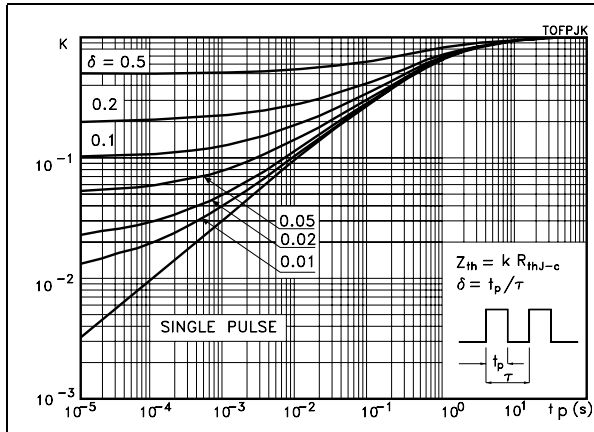
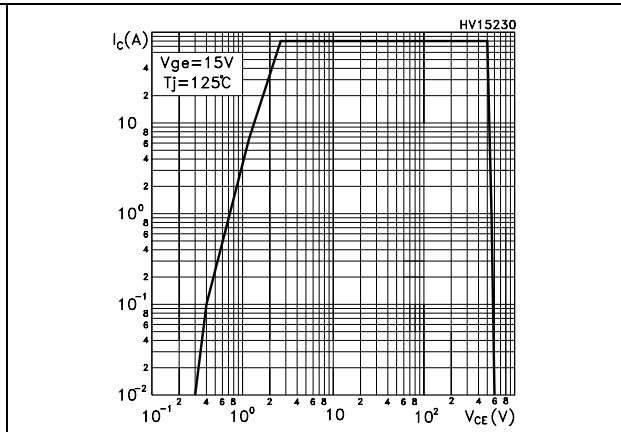


Figure 14. Turn-off SOA



3 Test Circuits

Figure 15. Test circuit for inductive load switching

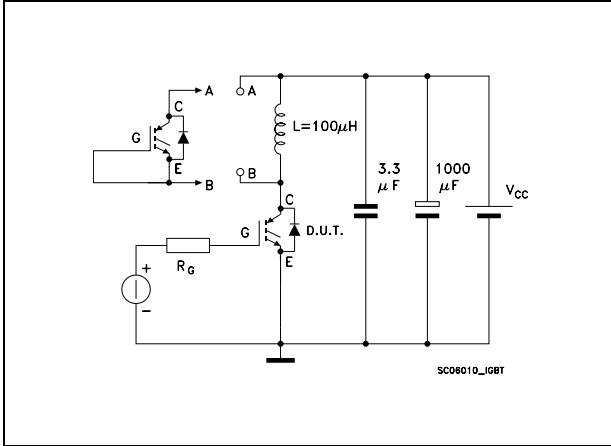


Figure 16. Gate charge test circuit

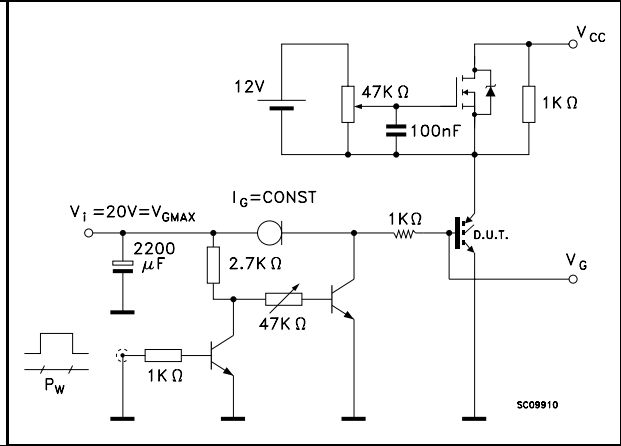
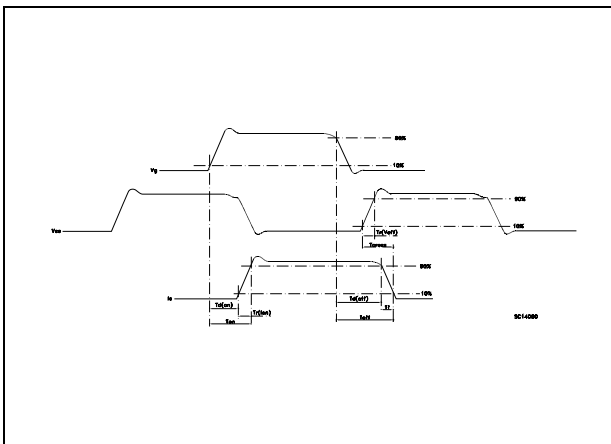


Figure 17. Switching waveform

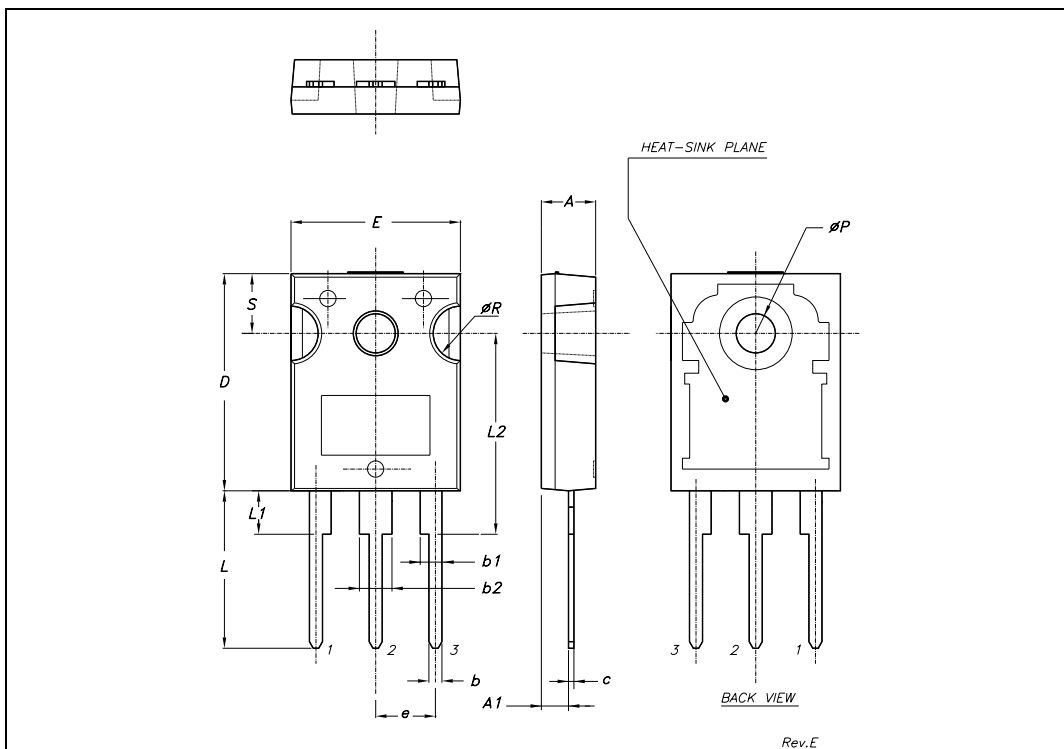


4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

TO-247 MECHANICAL DATA

| DIM. | mm. | | | inch | | |
|------|-------|-------|-------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 4.85 | | 5.15 | 0.19 | | 0.20 |
| A1 | 2.20 | | 2.60 | 0.086 | | 0.102 |
| b | 1.0 | | 1.40 | 0.039 | | 0.055 |
| b1 | 2.0 | | 2.40 | 0.079 | | 0.094 |
| b2 | 3.0 | | 3.40 | 0.118 | | 0.134 |
| c | 0.40 | | 0.80 | 0.015 | | 0.03 |
| D | 19.85 | | 20.15 | 0.781 | | 0.793 |
| E | 15.45 | | 15.75 | 0.608 | | 0.620 |
| e | | 5.45 | | | 0.214 | |
| L | 14.20 | | 14.80 | 0.560 | | 0.582 |
| L1 | 3.70 | | 4.30 | 0.14 | | 0.17 |
| L2 | | 18.50 | | | 0.728 | |
| øP | 3.55 | | 3.65 | 0.140 | | 0.143 |
| øR | 4.50 | | 5.50 | 0.177 | | 0.216 |
| S | | 5.50 | | | 0.216 | |



5 Revision history

Table 7. Revision history

| Date | Revision | Changes |
|-------------|----------|------------------|
| 28-Mar-2007 | 1 | Initial release. |

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